



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 - 1982.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
5. THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
6. SECTION B-B:  
THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
7. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
8. EXACT SHAPE OF EACH CORNER IS OPTIONAL.
9. JEDEC REFERENCE: MS-026

	SYMBOL	Common Dimensions		
		MIN.	NOM.	MAX.
Total Thickness:	A	1.40	1.50	1.60
Stand Off:	A1	0.05	0.10	0.15
Mold Thickness:	A2	1.35	1.40	1.45
Outer Lead Distance:	D	16.00 BSC.		
Package Size:	D1	14.00 BSC.		
Outer Lead Distance:	E	16.00 BSC.		
Package Size:	E1	14.00 BSC.		
	L	0.45	0.60	0.75
Lead count:	N	100		
Lead pitch:	e	0.50 BSC.		
L/F Thickness w/plating:	c	0.09	0.127	0.20
L/F Thickness w/o plating:	c1	0.09	—	0.16
L/F Thickness w/plating:	b	0.17	0.22	0.27
L/F Thickness w/o plating:	b1	0.17	0.20	0.23

Title: Package Outline Drawing

Pkg Type: LQFP/TQFP

Document No:

POD-250082

Product Family: LFMXO4

Pin Count: 100

Product Name: LFMXO4-010/015/025-TSG100

Pkg Size: 14x14 mm

Rev: A

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